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Should be replaced with:

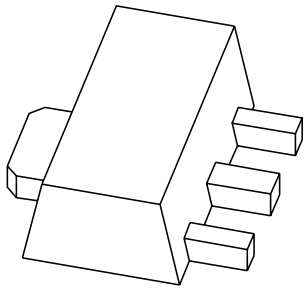
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Kind regards,

Team Nexperia

DATA SHEET



BF620; BF622 NPN high-voltage transistors

Product data sheet
Supersedes data of 1999 Apr 21

2004 Dec 14

NPN high-voltage transistors

BF620; BF622

FEATURES

- Low current (max. 50 mA)
- High voltage (max. 300 V).

APPLICATIONS

- Video output stages.

DESCRIPTION

NPN high-voltage transistor in a SOT89 plastic package.
PNP complements: BF621 and BF623.

MARKING

| TYPE NUMBER | MARKING CODE |
|-------------|--------------|
| BF620 | DC |
| BF622 | DA |

PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1 | emitter |
| 2 | collector |
| 3 | base |

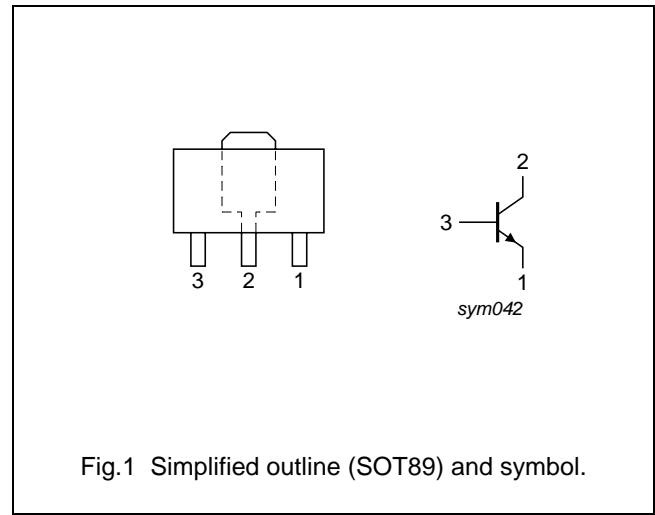


Fig.1 Simplified outline (SOT89) and symbol.

ORDERING INFORMATION

| TYPE NUMBER | PACKAGE | | |
|-------------|---------|--|---------|
| | NAME | DESCRIPTION | VERSION |
| BF620 | SC-62 | plastic surface mounted package; collector pad for good heat transfer; 3 leads | SOT89 |
| BF622 | | | |

NPN high-voltage transistors

BF620; BF622

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

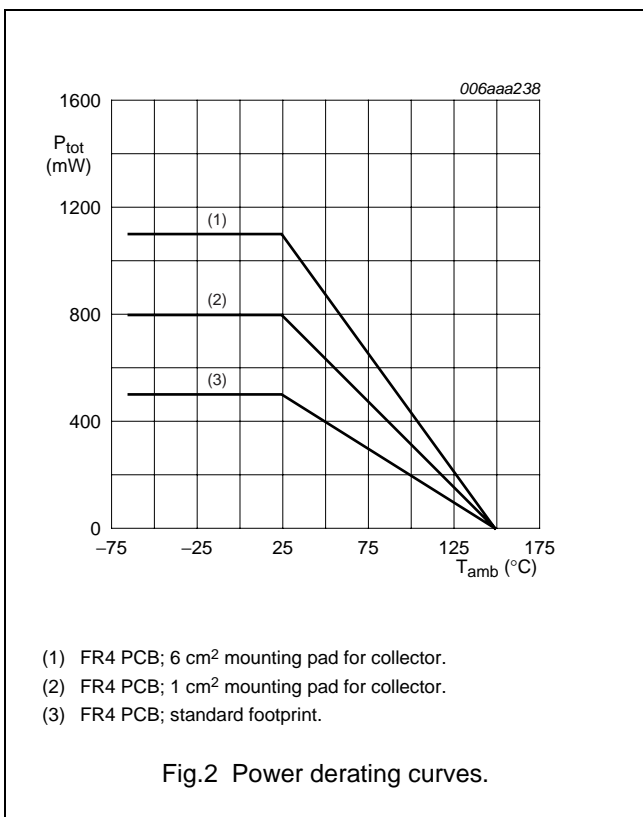
| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|------------------|---------------------------|--------------------------|------|------|------|
| V _{CBO} | collector-base voltage | open emitter | – | 300 | V |
| | BF620 | | | 250 | V |
| V _{CEO} | collector-emitter voltage | open base | – | 300 | V |
| | BF622 | | | 250 | V |
| V _{EBO} | emitter-base voltage | open collector | – | 5 | V |
| I _C | collector current (DC) | | – | 50 | mA |
| I _{CM} | peak collector current | | – | 100 | mA |
| I _{BM} | peak base current | | – | 50 | mA |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | – | 0.5 | W |
| | | note 1 | | 0.8 | W |
| | | note 2 | | 1.1 | W |
| | note 3 | | | | |
| T _{stg} | storage temperature | | –65 | +150 | °C |
| T _j | junction temperature | | – | 150 | °C |
| T _{amb} | ambient temperature | | –65 | +150 | °C |

Notes

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated and standard footprint.
2. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 1 cm².
3. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 6 cm².

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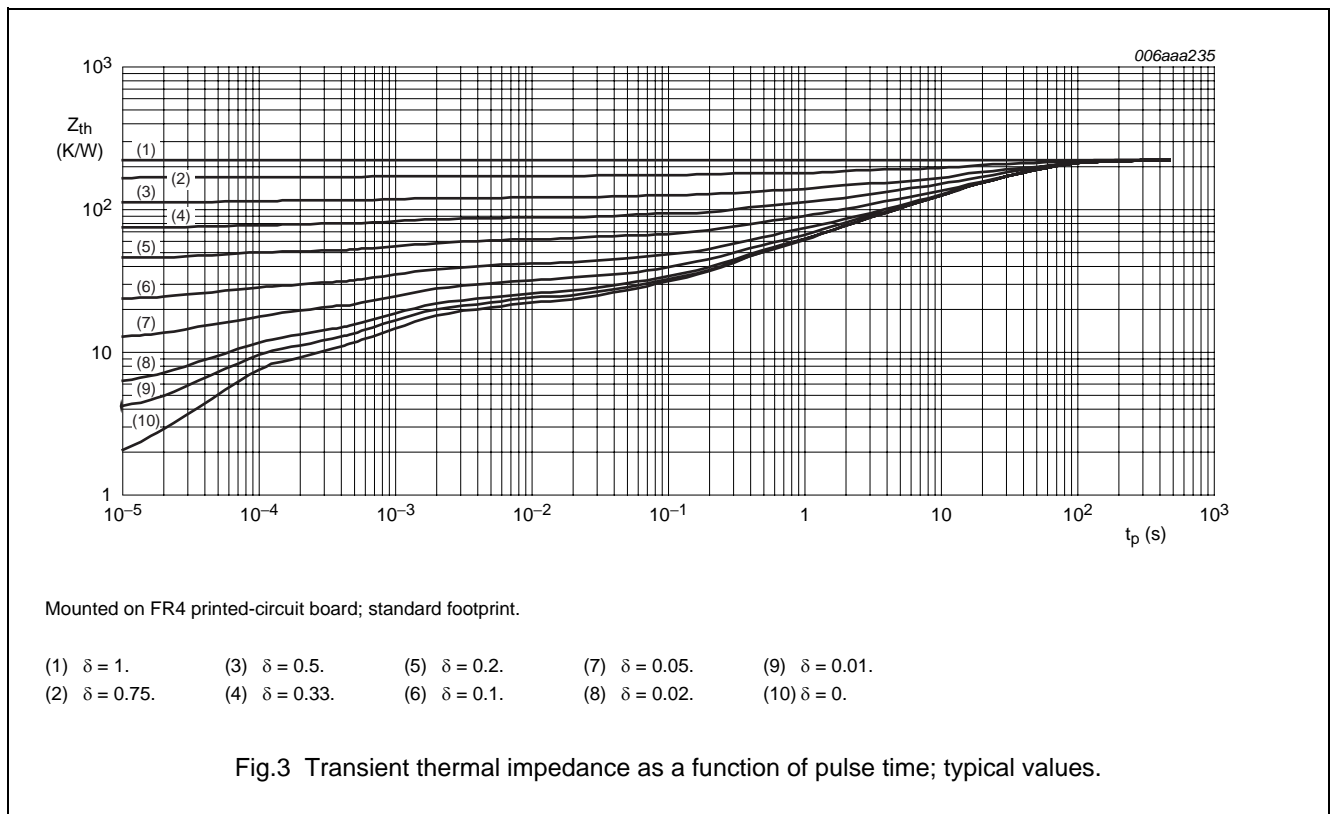
BF620; BF622

THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|----------------------|---|-------------|-------|------|
| R _{th(j-a)} | thermal resistance from junction to ambient | in free air | | |
| | | note 1 | 250 | K/W |
| | | note 2 | 156 | K/W |
| | | note 3 | 113 | K/W |
| R _{th(j-s)} | thermal resistance from junction to soldering point | | 30 | K/W |

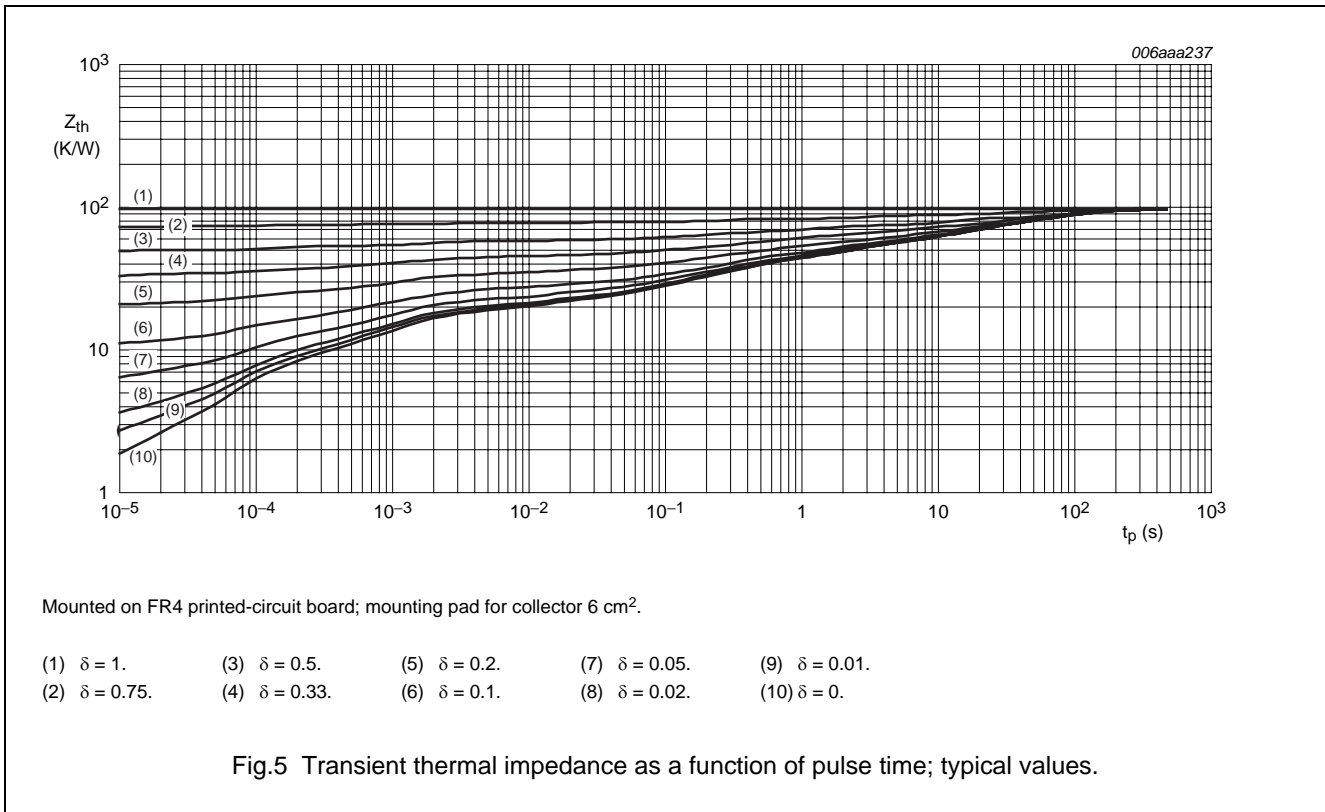
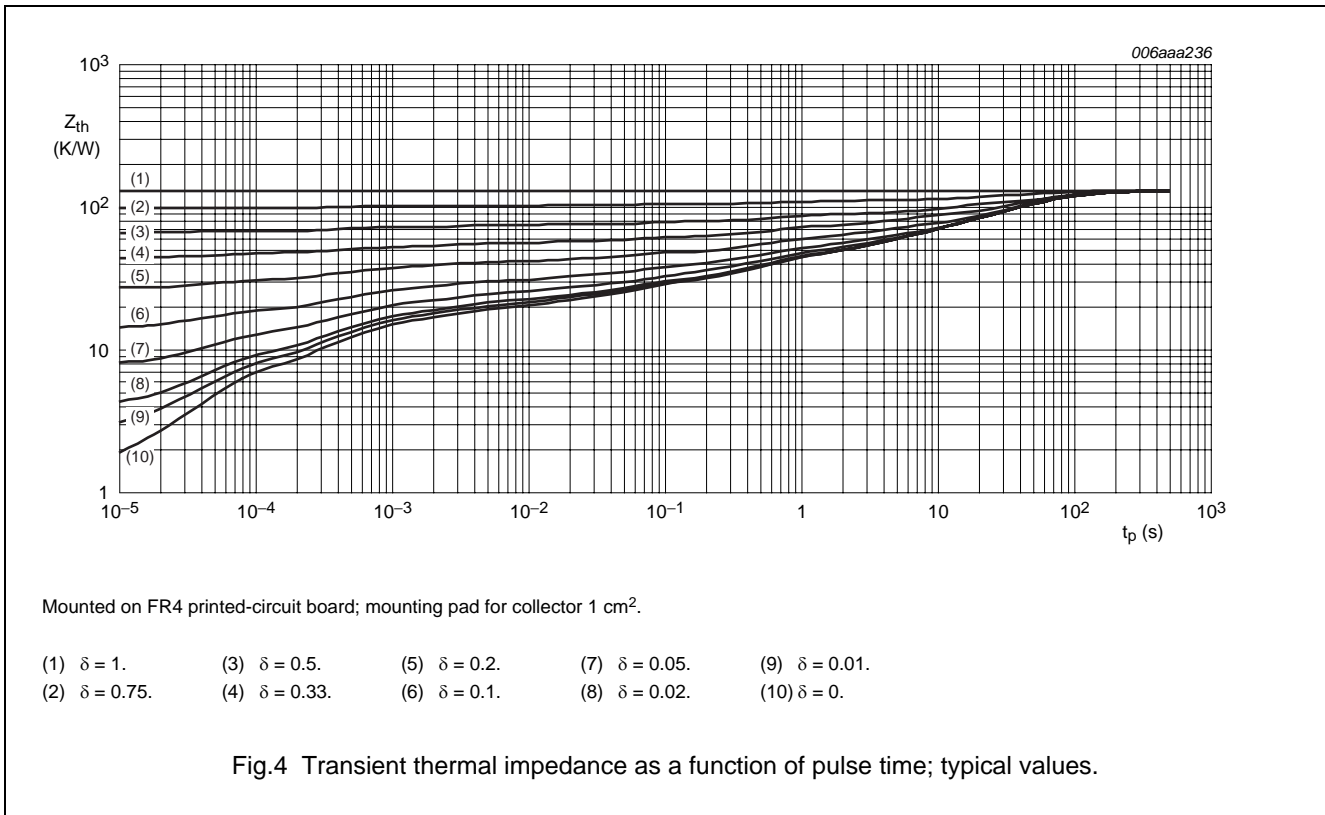
Notes

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3. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 6 cm².



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BF620; BF622



NPN high-voltage transistors

BF620; BF622

CHARACTERISTICS $T_{amb} = 25\text{ °C}$ unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|-------------|--------------------------------------|--|------|------|---------------|
| I_{CBO} | collector-base cut-off current | $I_E = 0\text{ A}; V_{CB} = 200\text{ V}$ | – | 10 | nA |
| | | $I_E = 0\text{ A}; V_{CB} = 200\text{ V}; T_j = 150\text{ °C}$ | – | 10 | μA |
| I_{EBO} | emitter-base cut-off current | $I_C = 0\text{ A}; V_{EB} = 5\text{ V}$ | – | 50 | nA |
| h_{FE} | DC current gain | $I_C = 25\text{ mA}; V_{CE} = 20\text{ V}$ | 50 | – | |
| V_{CEsat} | collector-emitter saturation voltage | $I_C = 30\text{ mA}; I_B = 5\text{ mA}$ | – | 600 | mV |
| C_{re} | feedback capacitance | $I_C = i_c = 0\text{ A}; V_{CE} = 30\text{ V}; f = 1\text{ MHz}$ | – | 1.6 | pF |
| f_T | transition frequency | $I_C = -10\text{ mA}; V_{CE} = 10\text{ V}; f = 100\text{ MHz}$ | 60 | – | MHz |

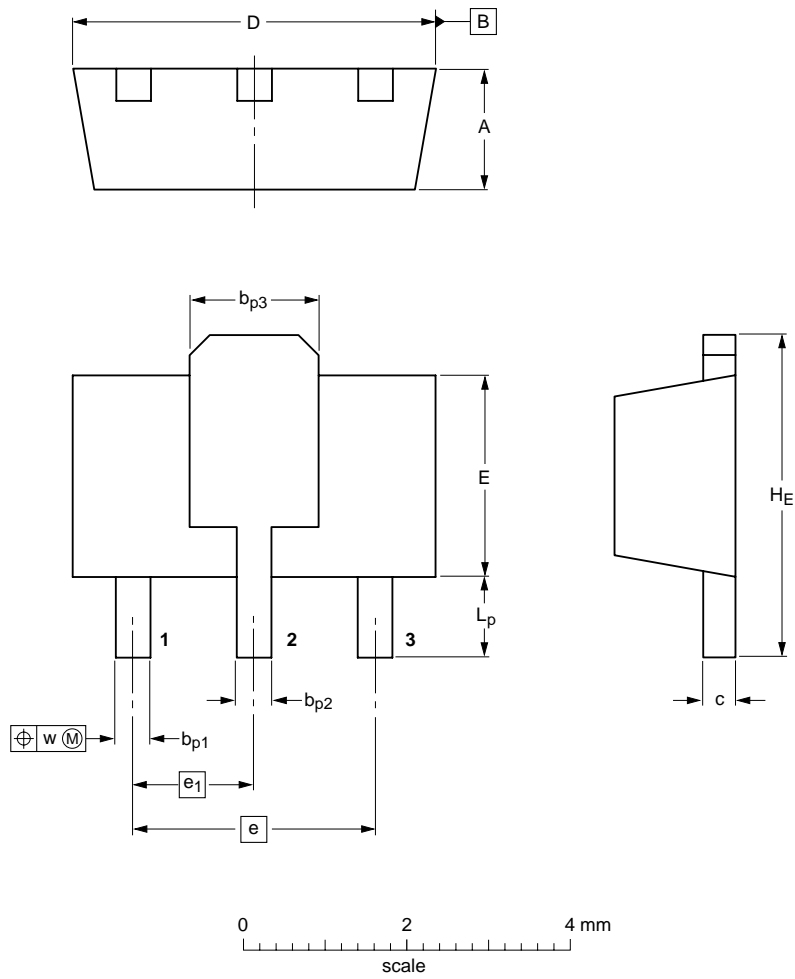
NPN high-voltage transistors

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PACKAGE OUTLINE

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads

SOT89



DIMENSIONS (mm are the original dimensions)

| UNIT | A | b _{p1} | b _{p2} | b _{p3} | c | D | E | e | e ₁ | H _E | L _p | w |
|------|------------|-----------------|-----------------|-----------------|--------------|------------|------------|-----|----------------|----------------|----------------|------|
| mm | 1.6 1.4 | 0.48 0.35 | 0.53 0.40 | 1.8 1.4 | 0.44 0.23 | 4.6 4.4 | 2.6 2.4 | 3.0 | 1.5 | 4.25 3.75 | 1.2 0.8 | 0.13 |

| OUTLINE VERSION | REFERENCES | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|--------|-------|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | |
| SOT89 | | TO-243 | SC-62 | | 04-08-03 06-03-16 |

NPN high-voltage transistors

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DATA SHEET STATUS

| DOCUMENT STATUS ⁽¹⁾ | PRODUCT STATUS ⁽²⁾ | DEFINITION |
|--------------------------------|-------------------------------|---|
| Objective data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary data sheet | Qualification | This document contains data from the preliminary specification. |
| Product data sheet | Production | This document contains the product specification. |

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: <http://www.nxp.com>

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Printed in The Netherlands

R75/04/pp10

Date of release: 2004 Dec 14

Document order number: 9397 750 13867





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